



Material Content Data Sheet



Sales Product Name		TLS805B1SJV		Issued		20. July 2018		
MA#		MA001323998						
Package		PG-DSO-8-44		Weight*		82.65 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.989	1.20	1.20	11963	11963
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		434	
	non noble metal	iron	7439-89-6	0.717	0.87		8677	
wire	non noble metal	copper	7440-50-8	29.121	35.23	36.15	352336	361555
	non noble metal	copper	7440-50-8	0.041	0.05	0.05	500	500
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1208
encapsulation	plastics	epoxy resin	-	4.592	5.56		55553	
	inorganic material	silicondioxide	60676-86-0	45.217	54.70	60.38	547078	603839
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9847	9847
plating	noble metal	silver	7440-22-4	0.650	0.79	0.79	7867	7867
glue	plastics	acrylic resin	-	0.081	0.10		974	
	noble metal	silver	7440-22-4	0.286	0.35	0.45	3455	4429
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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